```
ADVANTAGE - Elimi .tes interlaminar peeling of in: ated and
    cementing layers. Improves adhesive strength of conducting wiring
    layer. Improves reproducibility.
        Dwg.1/2|
DE- <TITLE TERMS> MULTILAYER; PRINT; CIRCUIT; ELECTRONIC; DEVICE; CEMENTED;
    LAYER; COVALENT; BOND; STRUCTURE; FORMING; SURFACE; INSULATE; RESIN;
    LAYER
DC- A85; L03; V04|
IC- <MAIN> H05K-003/46!
IC- <ADDITIONAL> H05K-003/381
MC- <CPI> A12-E07A; L03-H04E3|
MC- <EPI> V04-R05A; V04-R07P11
FS- CPI; EPI||
?s pn=jp 08335608
               1 PN=JP 08335608
      S6
?t s6/4/all
 6/4/1
DIALOG(R) File 351: Derwent WPI
(c) 2001 Derwent Info Ltd. All rts. reserv.
AA- 1997-097439/199709 |
XR- <XRAM> C97-031113|
XR- <XRPX> N97-080828|
TI- Spacer films for tape automated bonding - comprises 150 micron thick
    polyimide film.
PA- DU PONT TORAY CO LTD (DUPO ); TORAY IND INC (TORA )|
NC- 001|
NP- 0011
PN- JP 8335608
                  A 19961217 JP 95139362
                                             A 19950606 199709 BI
AN- <LOCAL> JP 95139362 A 199506061
AN- <PR> JP 95139362 A 19950606|
FD- JP 8335608
                  A H01L-021/60
LA- JP 8335608(4)|
AB- <BASIC> JP 8335608 A
        A new spacer film for tape automated bonding (TAB) is made of a
    polyimide film with a thickness of at least 150 mum.
        ADVANTAGE - The new films have good heat resistance and can be
    moulded at high temp. They can be repeatedly used.
        Dwg.0/0|
DE- <TITLE TERMS> SPACE; FILM; TAPE; AUTOMATIC; BOND; COMPRISE; MICRON;
    THICK; POLYIMIDE; FILM
DE- <ADDITIONAL WORDS> TAB
DC- A26; A85; G03; L03; P73; U11|
IC- <MAIN> H01L-021/60|
IC- <ADDITIONAL> B32B-027/34; C08G-073/10|
MC- <CPI> A05-J01B; A12-A01; A12-E07C; G03-B04; L04-C17D|
MC- <EPI> U11-E01B|
FS- CPI; EPI; EngPI||
?s pn=jp 8153833
               1 PN=JP 8153833
      S7
?t s7/4/all
 7/4/1
DIALOG(R) File 351: Derwent WPI
(c) 2001 Derwent Info Ltd. All rts. reserv.
IM- *Image available*
AA- 1996-331733/199633 |
XR- <XRAM> C96-104859|
XR- <XRPX> N96-279861|
TI- Semiconductor device mfg method for semiconductor IC - by sealing with
    resin after carrying out plasma processing on surface of a polyimide
    film formed on substrate
PA- SANYO ELECTRIC CO LTD (SAOL ) [
NC- 001|
```